



SF305 无卤阻燃型聚酰亚胺薄膜挠性覆铜板

SF305 Halogen-free PI film based flexible copper clad laminate (3-layer FCCL)

特点

- 不含卤素，阻燃性达到UL94V-0级。
- 优秀的挠曲性、耐热性、尺寸稳定性和电性能。
- 满足RoHS指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

应用领域

电脑、移动电话、数码相机、摄录机、办公自动化设备等。

FEATURES

- Halogen free, and Flammability UL94 V-0.
- Excellent flexibility, thermal resistance, dimensional stability and electrical properties.
- Compatible with EU RoHS directive, free of Pb, Hg, Cd, Cr⁶⁺, PBB, PBDE, etc..

APPLICATIONS

Computer, Mobile phone, Digital camera, VCR, OA equipment, etc..

性能表 GENERAL PROPERTIES

性能项目 Test Item	试验处理条件 Treatment Condition	单位 Unit	性能数据 Property Data		
			IPC 标准值 Standard	典型值 Typical Value	
				051813DR	051813SE
剥离强度 Peel Strength (90°)	A	N/mm	≥0.7	1.1	1.3
	288℃,5s		≥0.5	1.0	1.2
耐折性 (MIT法) Folding Endurance (MIT)	R0.8X4.9N	次 Times	-	>600	>350
热应力 Thermal Stress	288℃,20s	-	-	无分层、无起泡 No delamination	无分层、无起泡 No delamination
尺寸稳定性 Dimensional Stability	MD E-0.5/150 TD	%	±0.2	±0.1	±0.1
				±0.1	±0.1
耐化学性 (剥离强度保持率) Chemical Resistance	暴露化学品后 After Chemical Exposure	%	≥80	>85	>85
介电常数 (1MHz) Dielectric Constant(1MHz)	C-24/23/50	-	≤4.0	3.6	3.6
介质损耗角正切 (1MHz) Dissipation Factor (1MHz)	C-24/23/50	-	≤0.04	0.031	0.030
体积电阻率 (湿热) Volume Resistivity	C-96/35/90	MΩ · cm	≥10 ⁹	1.5x10 ⁹	2.0x10 ⁹
表面电阻 (湿热) Surface Resistance	C-96/35/90	MΩ	≥10 ⁵	5.0x10 ⁶	4.5x10 ⁶

注释 Explanations: C = 湿热处理条件 Humidity conditioning;
E = 恒温处理条件 Temperature conditioning.